



Material Content Data Sheet



Sales Product Name		IPD95R750P7		Issued		9. January 2019		
MA#		MA001798346						
Package		PG-TO252-3-341		Weight*		388.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.428	0.88	0.88	8816	8816
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		177	
	non noble metal	iron	7439-89-6	0.229	0.06		590	
	non noble metal	copper	7440-50-8	228.946	58.89	58.97	588759	589526
	non noble metal	aluminium	7429-90-5	1.531	0.39	0.39	3937	3937
wire	non noble metal	aluminium	7429-90-5	1.531	0.39	0.39	3937	3937
encapsulation	organic material	carbon black	1333-86-4	0.384	0.10		989	
	plastics	epoxy resin	-	11.660	3.00		29986	
	inorganic material	silicondioxide	60676-86-0	116.090	29.85	32.95	298537	329512
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9618	9618
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1309	1309
solder	non noble metal	tin	7440-31-5	0.061	0.02		158	
	noble metal	silver	7440-22-4	0.077	0.02		198	
	non noble metal	lead	7439-92-1	2.934	0.75	0.79	7545	7901
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		49	
	non noble metal	copper	7440-50-8	19.177	4.93	4.93	49317	49381
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com